

PCN Number:	20230322000.1	PCN Date:	March 22, 2023
Title:	Qualification of RFAB as an additional Fab site option for select HPA07 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jun 22, 2023	Sample Requests accepted until:	Apr 22, 2023*

***Sample requests received after April 22, 2023 will not be supported.**

Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DP1DM5	HPA07	200mm	RFAB	HPA07	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

Product Affected:

ADS1294CZXGR	ADS1296CZXGR	ADS1298CZXGR	SN1504010ZXGR
ADS1294CZXGT	ADS1296CZXGT	ADS1298CZXGT	
ADS1294IPAG	ADS1296IPAG	ADS1298IPAG	
ADS1294IPAGR	ADS1296IPAGR	ADS1298IPAGR	

Qualification Report
Approve Date 08-March-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ADS1298IPAGR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	140C	480 Hours	-	1/77/0	2/154/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0
ELFR	B2	ELFR	125C	48 Hours	-	1/1000/0	2/2000/0	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD CDM	-	200 Volts	-	-	3/9/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	3/9/0	-
ESD	E2	ESD HBM	-	2500 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-
LU	E4	LU	Per JESD78	-	-	3/9/0	3/9/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-

- QBS: Qual By Similarity
- Qual Device ADS1298IPAGR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or

other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disdains responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.